



Technical Bulletin

JOHNSON MANUFACTURING COMPANY
Princeton, Iowa 52768-0096

JOHNSON'S ANTI-DROSS POT WAFERS Part No. 41-50 Series

DESCRIPTION:

Johnson's Anti-Dross Pot Wafers help you recover up to 75% of the metal contained in the dirt and oxides on top of your solder pot. This unique product is combination of inorganic chlorides blended with a special carrier, that is then molded into a convenient wafer form. When carefully introduced into the pot, ie. under the surface of the solder, it disperses almost instantly throughout the entire pot. It brings dirt and dross to the surface, while retaining good metal. All that is left on top of the pot is a powdery dust to be skimmed off.

USAGE

Bring the solder pot to a temperature approximately 100 degrees F over the liquidus of the solder alloy, and stir well. For best results, introduce a pot wafer directly into the vortex created by a pneumatic mixer, or stir the pot with a device that holds a pot wafer under the surface of the solder. Stir repeatedly before skimming the pot.

Caution: When introducing any substance under the surface of molten solder, violent spattering may occur. Always wear protective clothing, gloves, sleeve protectors and full face shield. Use great care when introducing this product to a solder pot. Pot Wafers may also ignite producing flame and a volume of white smoke and fumes. Solder pots should always be well ventilated to handle fumes.

HANDLING:

Caution: Handle solder dross and skimmings with care to keep the dusting to an absolute minimum. Do NOT sweep up dross spills; these should be vacuumed to prevent lead from becoming airborne. Keep dross containers closed during storage.

Wear protective clothing and a full face shield when using Pot Wafers. Please refer to *OSHA Material Safety Data Sheet* for additional information.



TO ORDER CALL (800) 747-0030, FOR SUPPORT CALL (563) 289-5123, TO SEND FAX (563) 289-3825, EMAIL TO johnsonmfg@aol.com